ORIENT DISPLAY

Your Total LCD Solution Provider

Specification for TFT

AFR240320A0-2.0INTM

Revision V1.0

A	Orient Display
FR	TFT Type
240320	Resolution 240 x 320
A0	Serial A0
2.0	2.0'', Module Dimension 35.8x52.1x2.65 mm
I	IPS Display
N	Top: -20~+70°C; Tstr: -30~+80°C
T	Transmissive/Normally Black
M	Medium Brightness, 480cd/m2
/	No Touch Panel
/	Controller ST7789V
/	8/9/16/18Bit MCU Interface; 3/4SPI+16/18Bit RGB Interface; 3-line/4-line Serial Interface

Revision History

Date	Rev. No.	Page	Summary
2017.12.06	V1.0	ALL	FIRST ISSUE

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1.Basic Information

*** Description**

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit,back-light unit. The resolution of a 2.0'TFT-LCD contains 240x320 pixels, and can display up to 65K/262K colors.

1.1 Features

-Low Input Voltage: 3.3V(TYP)

-Display Colors of TFT LCD: 65K/262K colors

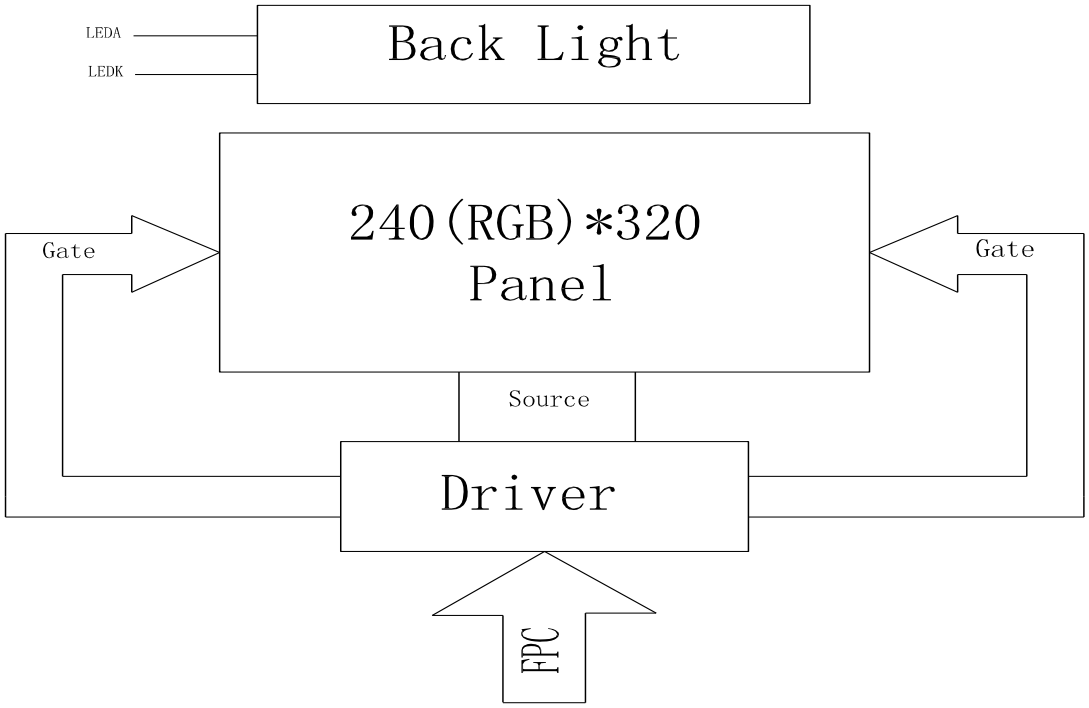
-Interface: 8/9/16/18Bit MCU Interface
3/4SPI+16/18Bit RGB Interface
3-line/4-line Serial Interface

General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	30.60(H)*40.80(V) (2.0inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K	colors	-
Number of pixels	240(RGB)*320	dots	-
Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.1275(H)*0.1275(V)	mm	-
Viewing angle	ALL	o'clock	-
Controller IC	ST7789V	-	-
Display mode	Transmissive/Normally Black	-	-
Operating temperature	-20～+70	℃	-
Storage temperature	-30～+80	℃	-

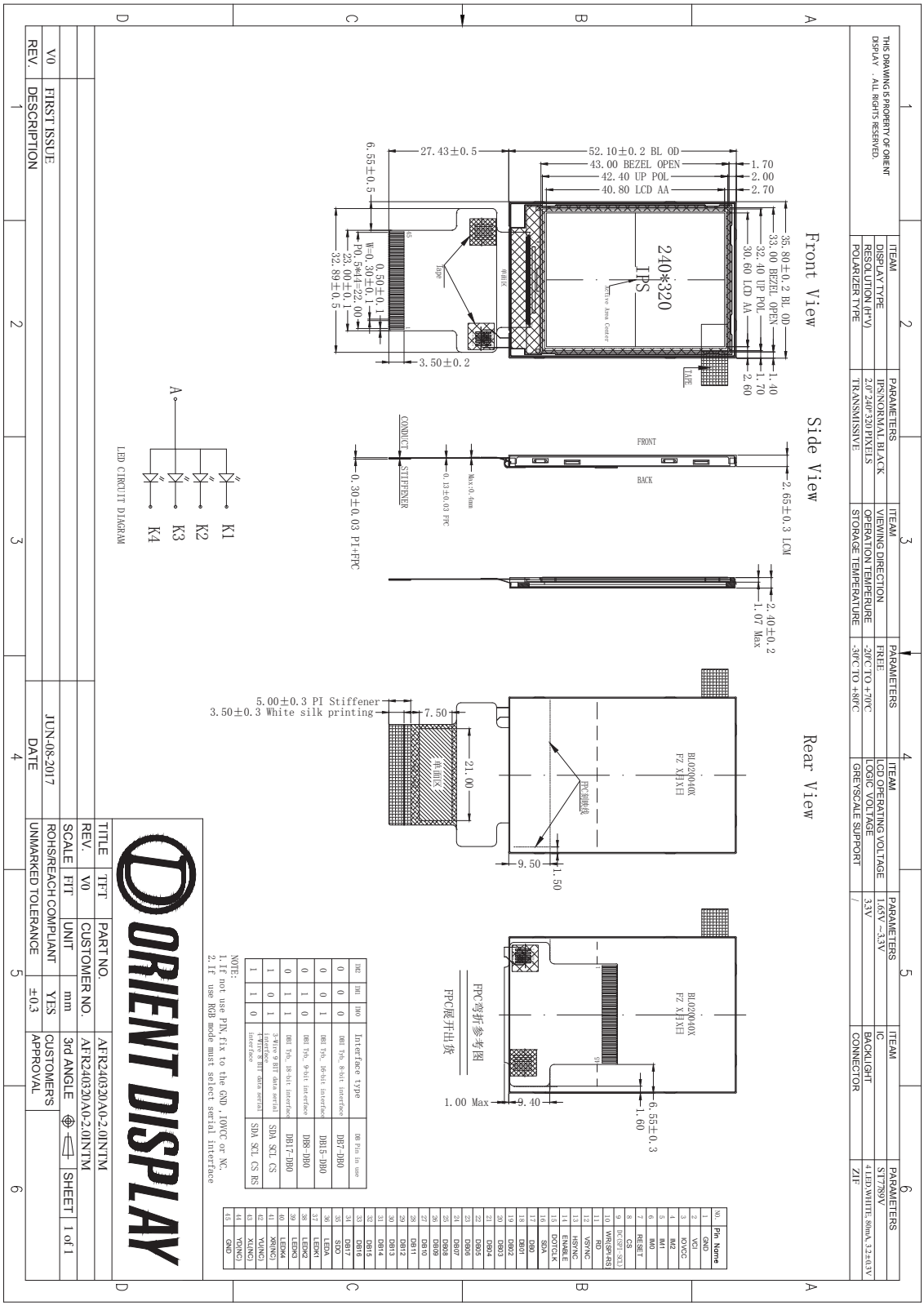
1.2 Mechanical Information

Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		35.8		mm	-
	Vertical(V)		52.1		mm	-
	Depth(D)		2.65		mm	-
Weight			9		g	-

2. Block Diagram



3.Outline Dimension



No.	Pin Name
1	GND
2	VCI
3	IOVCC
4	IM2
5	IM1
6	IM0
7	RESET
8	CS
9	DC(SPI-RS)
10	WR(SPI-RS)
11	RD
12	VSYNC
13	HSYNC
14	ENABLE
15	DOTCLK
16	SDA
17	DB00
18	DB01
19	DB02
20	DB03
21	DB04
22	DB05
23	DB06
24	DB07
25	DB08
26	DB09
27	DB10
28	DB11
29	DB12
30	DB13
31	DB14
32	DB15
33	DB16
34	DB17
35	SDO
36	LEDK1
37	LEDK1
38	LEDK2
39	LEDK2
40	LEDA4
41	XR(NC)
42	YU(NC)
43	XL(NC)
44	YD(NC)
45	GND

IM2	IM1	IM0	Interface type	DB Pin in use
0	0	0	DBI Typ. 8-bit interface	DB7-DB0
0	0	1	DBI Typ. 16-bit interface	DB15-DB0
0	1	0	DBI Typ. 9-bit interface	DB8-DB0
0	1	1	DBI Typ. 18-bit interface	DB17-DB0
1	0	1	3-wire 9 BIT data serial interface	SDA SCL CS
1	1	0	4-wire 8 BIT data serial interface	SDA SCL CS RS

NOTE:
1. If not use PIN,fix to the GND ,IOVCC or NC.
2. If use RGB mode must select serial interface

DISPLAY TYPE	IPS/NORMAL BLACK
RESOLUTION (H*V)	2.0" 240*320 PIXELS
POLARIZER TYPE	TRANSMISSIVE
VIEWING DIRECTION	OPERATION TEMPERURE
	STORAGE TEMPERATURE
LCD OPERATING VOLTAGE	1.65V~3.3V
LOGIC VOLTAGE	3.3V
GREYSCALE SUPPORT	/
IC	ST7789V
BACKLIGHT	4 LED,WHITTE,80mA,3.2±0.1V
CONNECTOR	ZIF

FRE:	-20°C TO +70°C
	-30°C TO +80°C

REV.	DESCRIPTION	DATE
V0	FIRST ISSUE	JUN-08-2017

TITLE	TFT
REV.	V0
SCALE	FIT
UNIT	mm
ROHS/REACH COMPLIANT	YES
UNMARKED TOLERANCE	±0.3
PART NO.	AFR240320A0-2.0INTM
CUSTOMER NO.	AFR240320A0-2.0INTM
3rd ANGLE	SHEET
CUSTOMER'S APPROVAL	

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4.Input terminal Pin Assignment

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	VCI	Supply voltage(3.3V).	P
3	IOVCC	Supply voltage(1.65-3.3V).	P
4	IM2	MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface.	I
5	IM1	Fix this pin at VCI and GND.	I
6	IM0		I
7	RESET	This signal will reset the device and must be applied to properly initialize the chip.	I
8	CS	Chip select input pin (“Low” enable). fix this pin at VCI or GND when not in use.	I
9	DC(SPI-SCL)	-Display data/command selection pin in parallel interface. -This pin is used to be serial interface clock. DC=’1’: display data or parameter. DC=’0’: command data. -If not used, please fix this pin at VDDI or DGND.	I
10	WR(SPI-RS)	-Write enable in MCU parallel interface. - Display data/command selection pin in 4-line serial interface. - Second Data lane in 2 data lane serial interface. -If not used, please fix this pin at VDDI or DGND.	I
11	RD	Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use.	I
12	VSYNC	Frame synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
13	HSYNC	Line synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
14	ENABLE	Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
15	DOTCLK	Dot clock signal for RGB interface operation. Fix this pin at VCI or GND when not in use.	I
16	SDA	Serial input signal.	I

		The data is latched on the rising edge of the SCL signal. fix this pin at VCI or GND when not in use.	
17-34	DB0-DB17	18-bit parallel bi-directional data bus for MCU system and RGB interface mode . Fix to GND level when not in use	I/0
35	SDO	SPI interface output pin. -The data is output on the falling edge of the SCL signal. -If not used, let this pin open.	O
36	LEDA	Anode pin of backlight	P
37	LEDK1	Cathode pin OF backlight	P
38	LEDK2	Cathode pin OF backlight	P
39	LEDK3	Cathode pin OF backlight	P
40	LEDK4	Cathode pin OF backlight	P
41	XR	Touch panel Right Glass Terminal. NC.	A/D
44	YU	Touch panel Top Film Terminal. NC.	A/D
43	XL	Touch panel LIFT Glass Terminal. NC.	A/D
42	YD	Touch panel Bottom Film Terminal. NC.	A/D
45	GND	Ground.	P

5.LCD Optical Characteristics

5.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	Θ=0 Normal viewing angle	640	800			
Response time	Rising	$T_{R+}T_F$		--	30	40	msec	
	Falling							
Color gamut		S(%)		--	60	--	%	
Color Filter Chromacicity	White	W_X		0.2594	0.2994	0.3394		
		W_Y		0.2777	0.3177	0.3577		
	Red	R_X		0.5976	0.6176	0.6376		
		R_Y		0.3308	0.3508	0.3708		
	Green	G_X		0.2964	0.3164	0.3364		
		G_Y		0.5671	0.5871	0.6071		
	Blue	B_X		0.1252	0.1452	0.1652		
		B_Y		0.0514	0.0714	0.0914		
Viewing angle	Hor.	Θ_L	CR>10	--	80	--		
		Θ_R		--	80	--		
	Ver.	Θ_U		--	80	--		
		Θ_D		--	80	--		
Option View Direction		ALL						

5.2 Measuring Condition

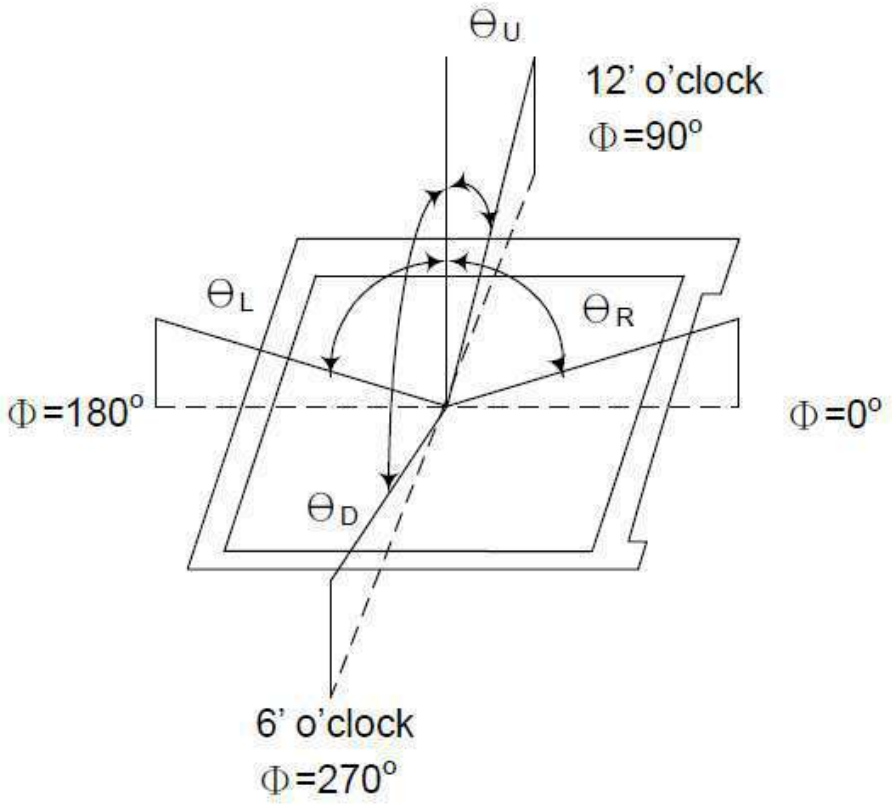
■ Measuring surrounding：dark room

■ Ambient temperature：25±2℃

■ 15min. warm-up time.

5.3 Measuring Equipment

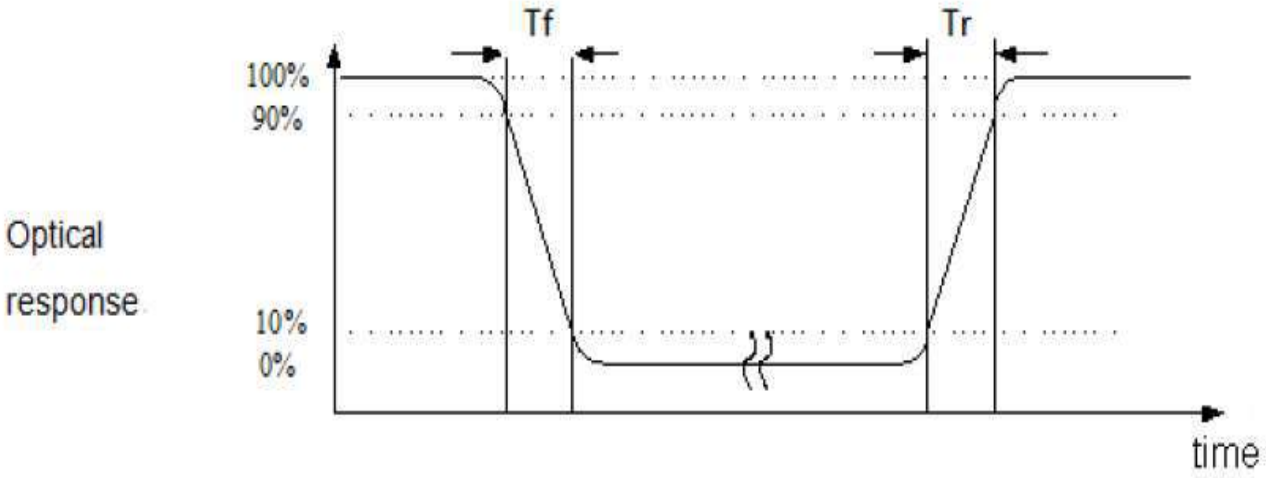
Note (1) Definition of Viewing Angle:



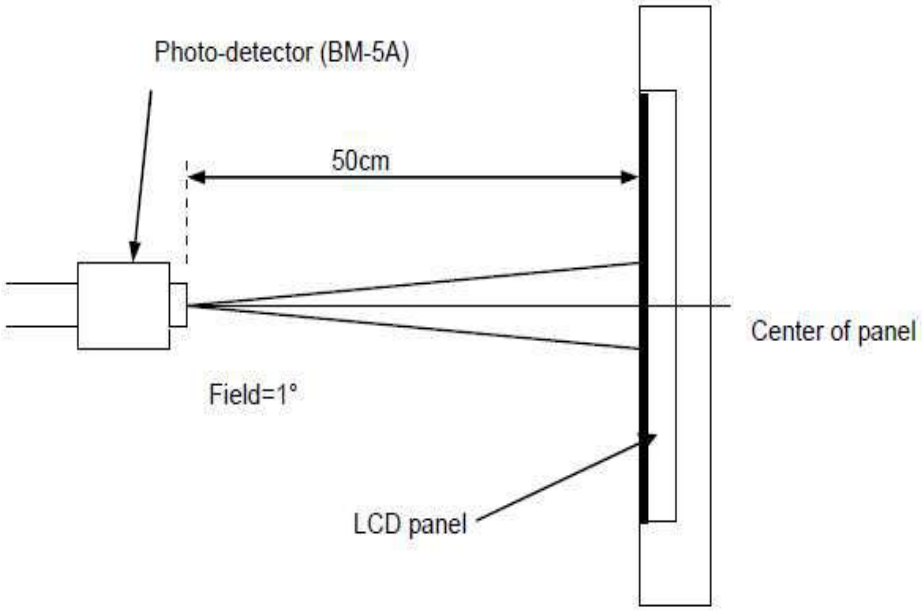
Note (2) Definition of Contrast Ratio (CR):
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

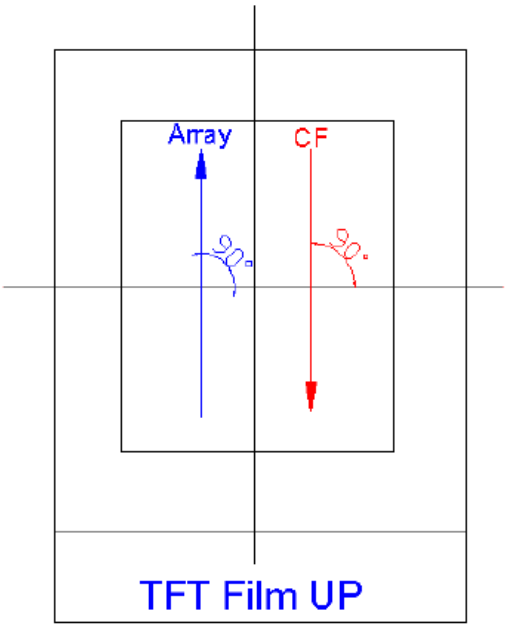
Note (3) Definition of Response Time: Sum of T_R and T_F



Note (4) Definition of optical measurement setup



Note (5) Rubbing Direction (The different Rubbing Direction will cause the different optima view direction.)



6. Electrical Characteristics

6.1 Absolute Operation Rating (Ta=25 VSS=0V)

Item	Symbol	Rating	Unit
Supply Voltage	VCI	-0.3~4.6	**V**
Digital interface supply Voltage	IOVCC	-0.3~4.6	**V**
Operating temperature	T_{OP}	-20~+70	℃
Storage temperature	T_{ST}	-30~+80	℃

Note: If one of the above items is exceeded its maximum limitation momentarily, the quality of the product may be degraded.
Absolute maximum limitation, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the recommend range.

6.2 DC Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Supply Voltage	VCI	2.4	3.3	3.6	V	
Digital interface supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal mode Current consumption	IDD	--	9	--	mA	
Level input voltage	V_{IH}	0.7 IOVCC		IOVCC	V	
	V_{IL}	GND		0.3 IOVCC	V	
Level output voltage	V_{OH}	0.8 IOVCC		IOVCC	V	
	V_{OL}	GND		0.2 IOVCC	V	

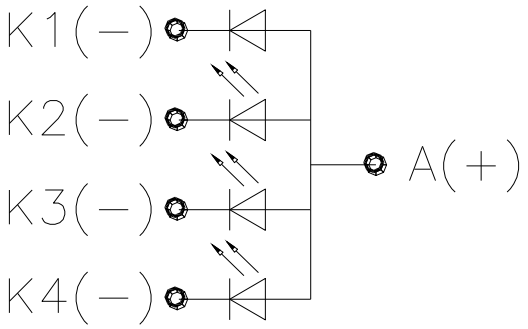
6.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 4 chips White LED

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	60	80	--	mA	
Forward Voltage	V_F	--	3.2	--	V	
LCM Luminance	L_V	430	480	--	cd/m2	Note3
LED life time	Hr	50000	--	--	Hour	Note1,2
Uniformity	AVg	80	--	--	%	Note3

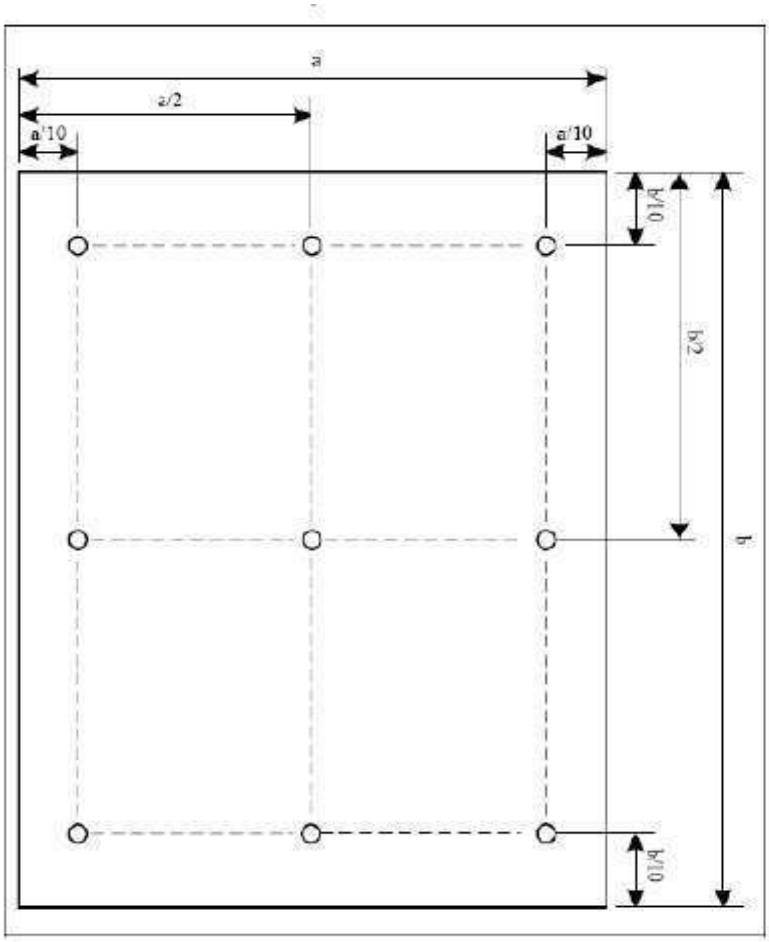
Note (1) LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 ℃, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note (2) The “LED life time” is defined as the module brightness decrease to 50% original brightness at Ta=25℃ and IL=80mA. The LED lifetime could be decreased if operating IL is larger than 80mA. The constant current driving method is suggested.



BLU CIRCUIT DIAGRAM

NOTE 3：Luminance Uniformity of these 9 points is defined as below:

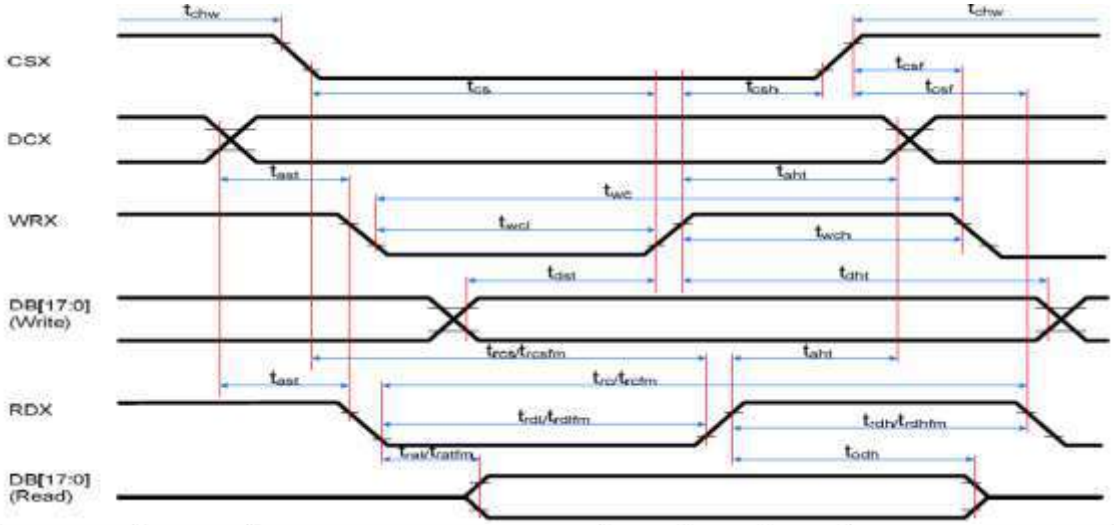


$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$

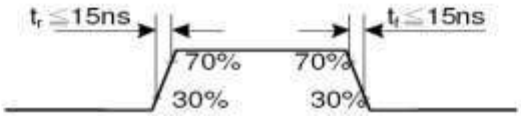
7. AC Characteristic

7.1 Display Parallel 8/16-bit Interface Timing Characteristics (8080 system)

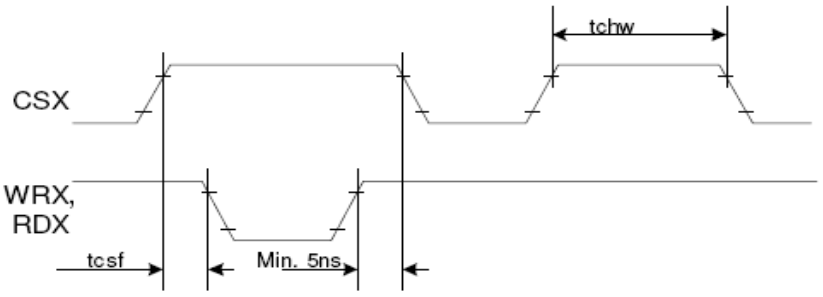


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	10	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 °C, IOVCC=1.65V to 2.8V, VCI=2.6V to 3.3V, GND=0V

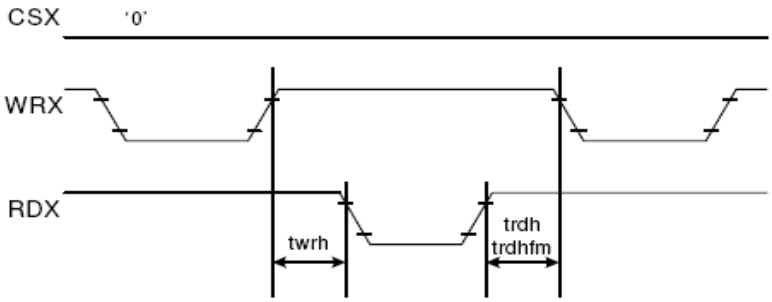


CSX timings :



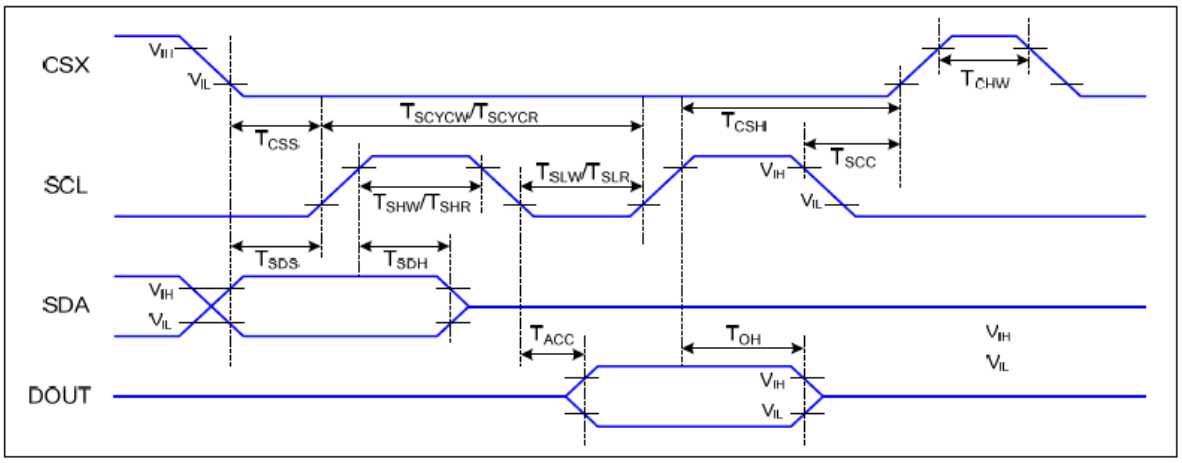
Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

Write to read or read to write timings:



Note: Logic high and low levels are specified as 30% and 70% of IOVCC for Input signals.

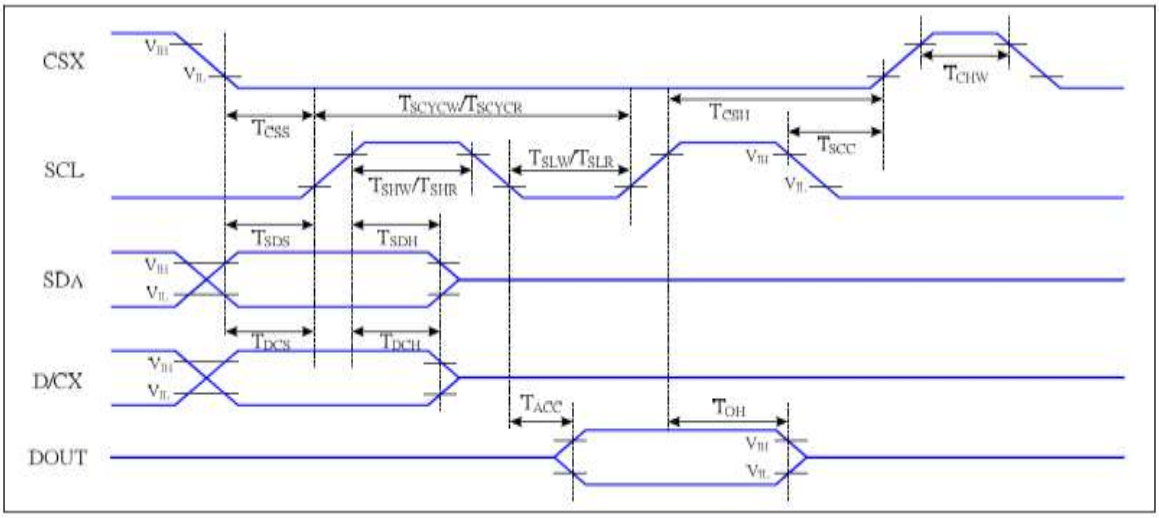
7.2 Display Serial Interface Timing Characteristics (3-line SPI system)



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 ℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select “H” pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL “H” pulse width (Write)	15		ns	
	T_{SLW}	SCL “L” pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL “H” pulse width (Read)	60		ns	
	T_{SLR}	SCL “L” pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

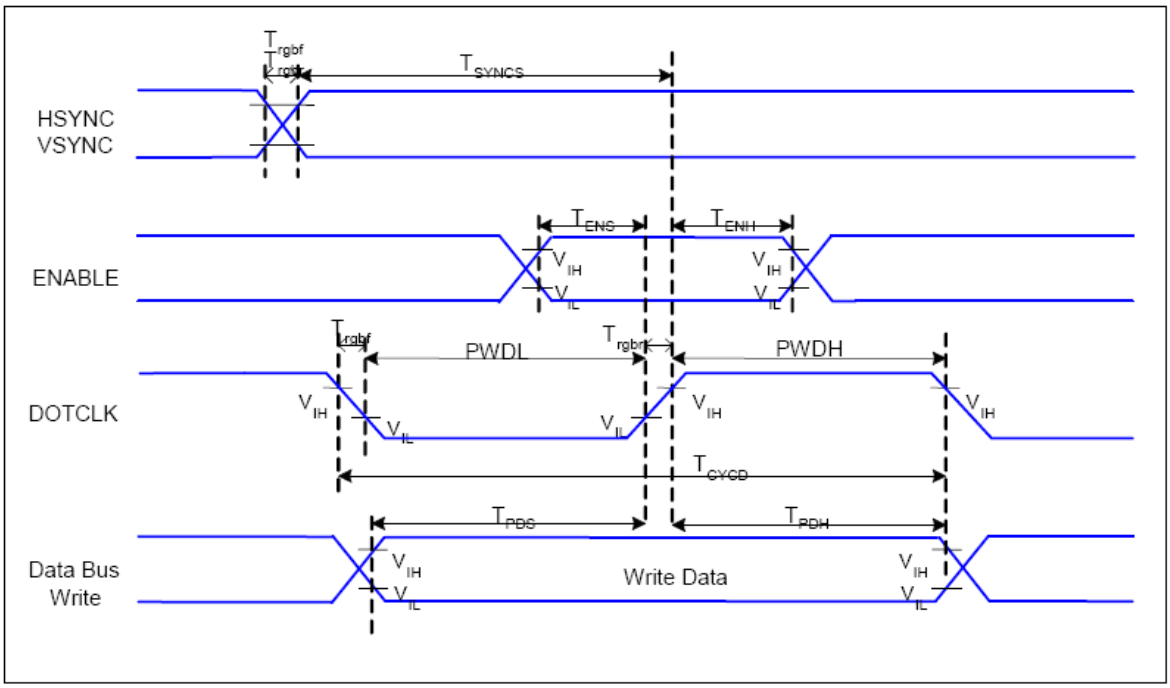
7.3 Display Serial Interface Timing Characteristics (4-line SPI system)



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

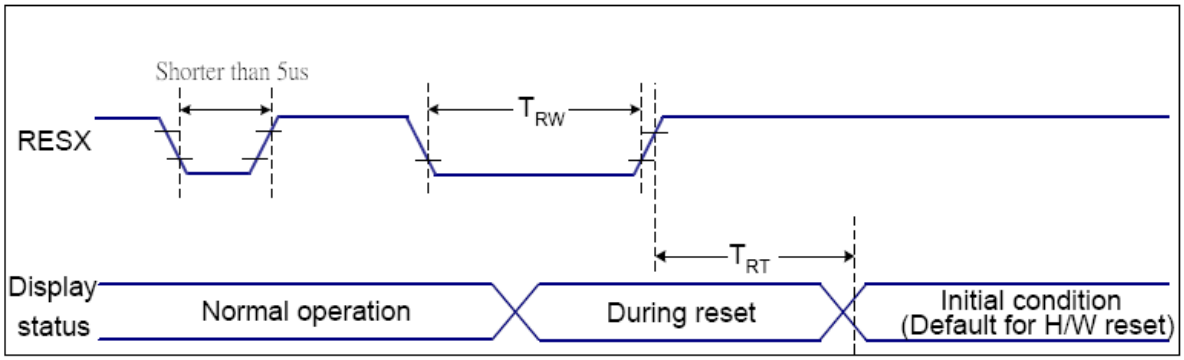
7.4 Parallel RGB Interface Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	25	-	ns	
	T_{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T_{PDS}	PD Data Setup Time	50	-	ns	
	T_{PDH}	PD Data Hold Time	50	-	ns	

7.5 Reset Timing Characteristics



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Notes:

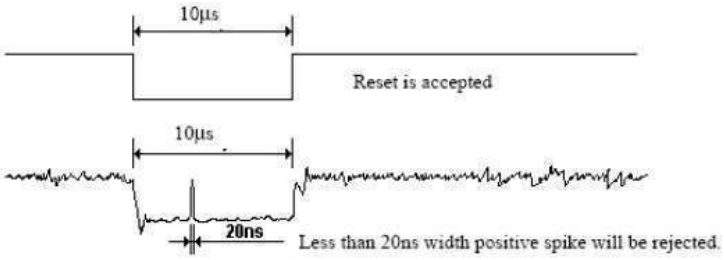
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

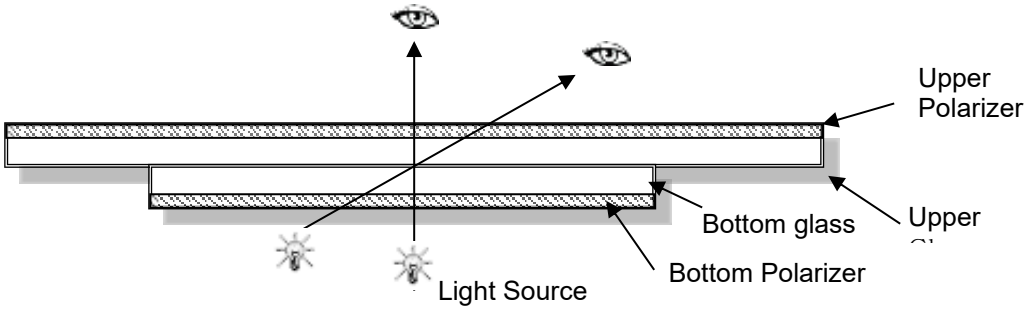
8.LCD Module Out-Going Quality Level

8.1 VISUAL & FUNCTION INSPECTION STANDARD

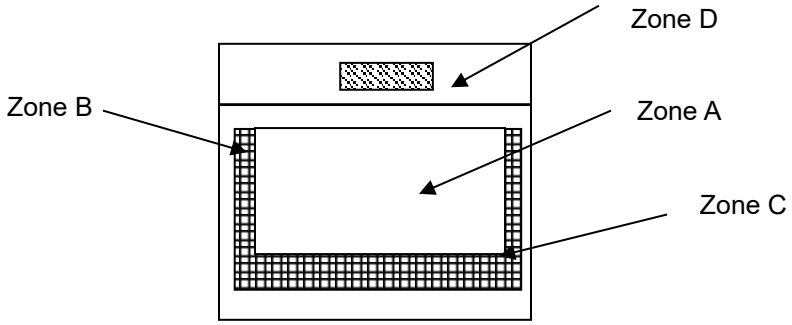
8.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

Temperature : 25±5℃
Humidity : 65%±10%RH
Viewing Angle : Normal viewing Angle.
Illumination: Single fluorescent lamp (300 to 700Lux)
Viewing distance:30-50cm



8.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)
Zone B : Viewing Area except Zone A
Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)
Zone D : IC Bonding Area
Note:
As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

8.1.3 Sampling Plan

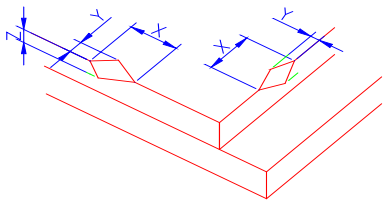
According to GB/T 2828-2003 ; , normal inspection, Class Ⅱ
AQL:

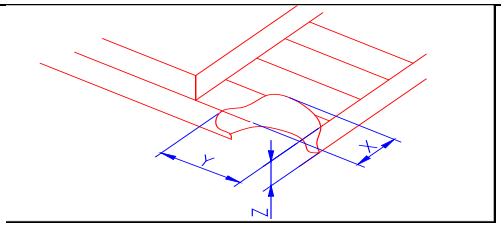
Major defect	Minor defect
0.65	1.5

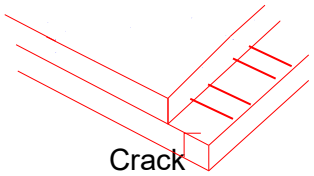
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot Line defect	Light dot，Dim spot,Polarizer Bubble ; Polarizer accidented spot.	
6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

8.1.4 Criteria (Visual)

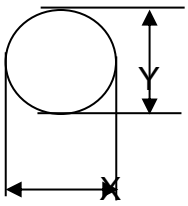
<table>
<tr><th>Number</th><th>Items</th><th>Criteria(mm)</th></tr>
<tr><td rowspan="3">1.0 LCD Crack/Broken
NOTE:
X: Length
Y: Width
Z: Height
L: Length of ITO,
T: Height of LCD</td><td>(1) The edge of LCD broken</td><td>

<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr>
</table></td></tr>
<tr><td>(2)LCD corner broken</td><td>

<table>
<tr><th>X</th><th>Y</th><th>Z</th></tr>
<tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr>
</table></td></tr>
<tr><td>(3) LCD crack</td><td>
Crack
Not allowed</td></tr>
</table>

2.0

Spot defect



Φ=(X+Y)/2

① light dot（LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain）

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.10	Ignore		Ignore
0.10<Φ≤0.20	3(distance≧10mm)		
0.20<Φ≤0.25	2		
Φ>0.3	0		

②Dim spot（LCD/TP/Polarizer dim dot, light leakage、dark spot）

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.1	Ignore		Ignore
0.10<Φ≤0.20	3(distance≧10mm)		
0.20<Φ≤0.25	2		
Φ>0.3	0		

③ Polarizer accidented spot

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.3<Φ≤0.5	2(distance≧10mm)		
Φ>0.5	0		

④Pixel bad points（light dot，Dim dot，color dot）

Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.1	Ignore		Ignore
0.15<Φ≤0.2	2(distance≧10mm)		
Φ>0.2	0		

⑤ Polarizer Bubble

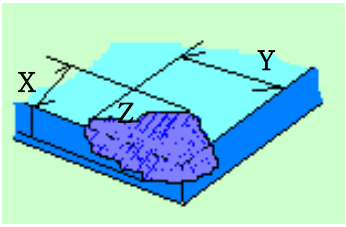
Zone / Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		Ignore
0.3<Φ≤0.4	3(distance≧10mm)		
0.4<Φ≤0.5	2		
Φ>0.5	0		

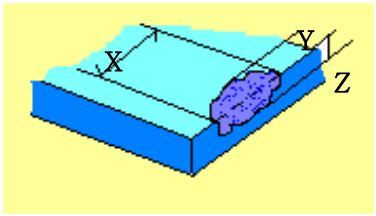
<table>
<tr><td>3.0</td><td>Line defect (LCD/TP /Polarizer backlight black/white line, scratch, stain)</td><td>
<table>
<tr><td rowspan="2">Width(mm)</td><td rowspan="2">Length(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.03</td><td>Ignore</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.03<W≤0.04</td><td>L≤3.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.04<W≤0.05</td><td>L≤2.0</td><td colspan="2">N≤1</td></tr>
<tr><td>0.05<W</td><td colspan="4">Define as spot defect</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>Electronic Components SMT</td><td>Not allow missing parts，solderless connection，cold solder joint，mismatch，The positive and negative polarity opposite</td></tr>
<tr><td>5.0</td><td>Display color& Brightness</td><td>1. Color：Measuring the color coordinates, The measurement standard according to the datasheet or samples.
2. Brightness：Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.</td></tr>
</table>

<table>
<tr><td rowspan="3">6.0</td><td rowspan="3">RTP Related</td><td>TP film bubble/ accidented spot</td><td>
<table>
<tr><td rowspan="2">Size Φ(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.1</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr>
<tr><td>0.1<Φ≤0.2</td><td colspan="2">3（distance≧10mm）</td></tr>
<tr><td>0.25<Φ≤0.3</td><td colspan="2">2</td></tr>
<tr><td>Φ>0.3</td><td colspan="2">0</td></tr>
</table>
</td></tr>
<tr><td>TP film scratch</td><td>
<table>
<tr><td rowspan="2">Width(mm)</td><td rowspan="2">Length(mm)</td><td colspan="3">Acceptable Qty</td></tr>
<tr><td>A</td><td>B</td><td>C</td></tr>
<tr><td>Φ≤0.03</td><td>Ignore</td><td colspan="2">Ignore</td><td rowspan="3">Ignore</td></tr>
<tr><td>0.03<W≤0.04</td><td>L≤3.0</td><td colspan="2">N≤2</td></tr>
<tr><td>0.04<W≤0.05</td><td>L≤2.0</td><td colspan="2">N≤1</td></tr>
<tr><td>0.05<W</td><td colspan="4">Define as spot defect</td></tr>
</table>
</td></tr>
<tr><td>Assembly deflection</td><td>beyond the edge of backlight ≤0.2mm</td></tr>
</table>

<table>
<tr><td rowspan="3"></td><td rowspan="3"></td><td>Bulge
(undulation included)</td><td colspan="2">The ITO film plumped below 0.40mm, it’s ok.

<0.4mm</td></tr>
<tr><td>Newton Ring</td><td>Newton Ring area>1/3 TP area NG
Newton Ring area≤1/3 TP area OK</td><td>

 </td></tr>
<tr><td>TP corner broken
X：length
Y：width
Z：height</td><td>*<table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>X≤ 3mm</td><td>Y≤ 3mm</td><td>Z<COVER thickness</td></tr></table>
*Circuitry broken is not allowed.</td><td></td></tr>
</table>

		TP edge broken X：length Y：width Z：height	X: X≤ 4mm; Y: Y≤ 2mm; Z: Z<COVER thickness * Circuitry broken is not allowed.	

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed

9.Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	70℃,96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-20℃, 96HR	
High Temperature Storage	80℃, 96HR	
Low Temperature Storage	-30℃, 96HR	
High Temperature & High Humidity Storage	+60℃, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-30℃,30 min ↔ 80℃,30 min, Change time:5min 20CYC.	
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15℃~35℃, 30%~60%).	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80㎝(MEDIUM BOX)	

Remark:

1.The test samples should be applied to only one test item.

2.Sample size for each test item is 5~10pcs.

3.For Damp Proof Test, Pure water(Resistance＞10MΩ) should be used.

4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.

5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

10. Cautions and Handling Precautions

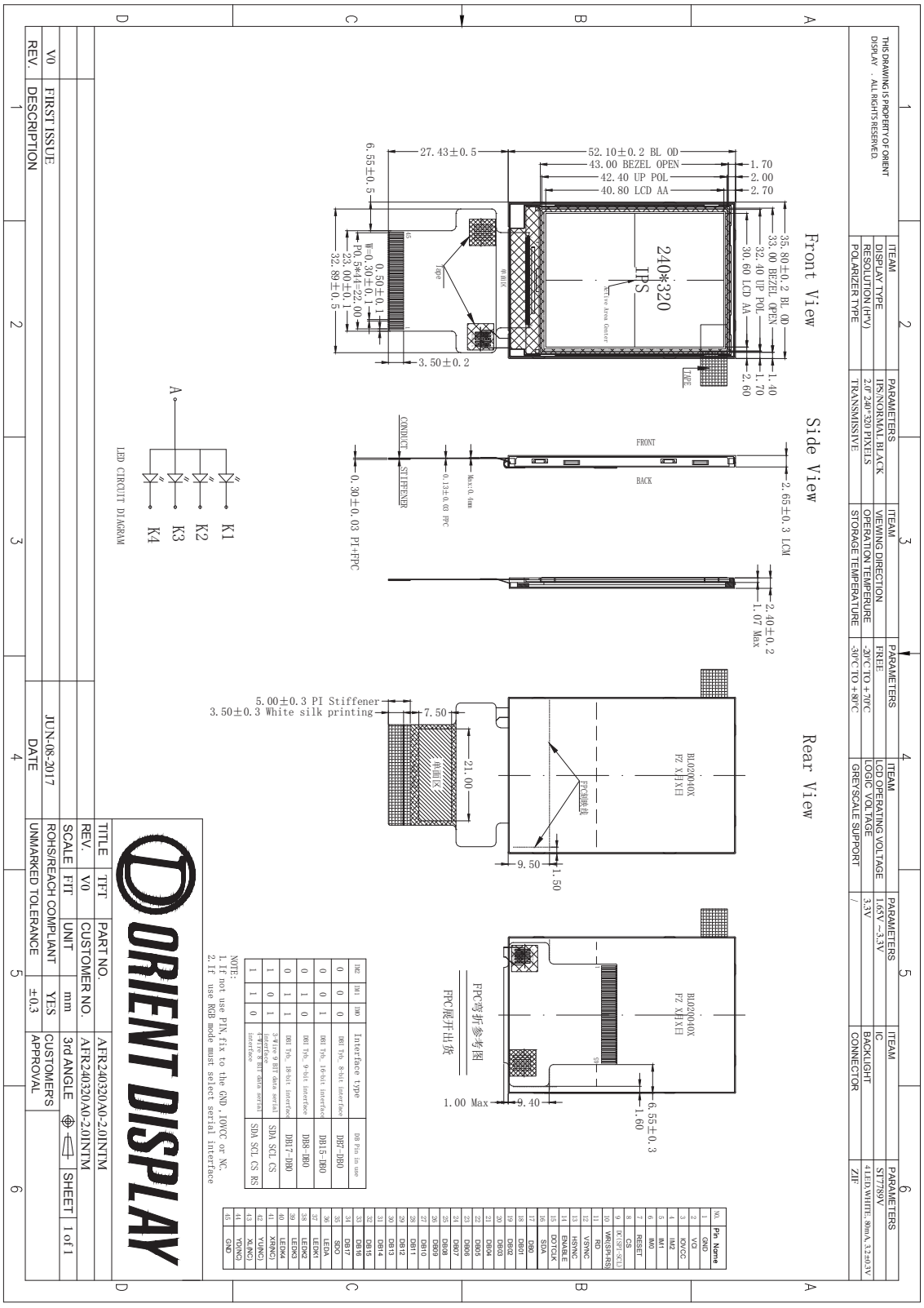
10.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.
Do not warp or twist the module during assembly work.
(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
(4) Do not allow drops of water or chemicals to remain on the display surface.
If you have the droplets for a long time, staining and discoloration may occur.
(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
(8) Protect the module from static; it may cause damage to the CMOS ICs.
(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
(10) Do not disassemble the module.
(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
(12) Pins of I/F connector shall not be touched directly with bare hands.
(13) Do not connect, disconnect the module in the “Power ON” condition.
(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence &6.2 Power Off Sequence

10.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.
It is highly recommended to store the module with temperature from 0 to 35 ℃ and relative humidity of less than 70%
(2) Do not store the TFT-LCD module in direct sunlight.
(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

11. Packing


Front View
Side View
Rear View
240*320
IPS
LED CIRCUIT DIAGRAM
K1
K2
K3
K4
ORIENT DISPLAY
AFR240320A0-2.0INTM
AFR240320A0-2.0INTM
FIRST ISSUE
JUN-08-2017